



# INTEGRATED CIRCUIT

## TECHNICAL DATA

# TA7207P, TA7208P

TOSHIBA BIPOLAR LINEAR INTEGRATED CIRCUIT  
SILICON MONOLITHIC

AUDIO POWER AMPLIFIER

DESIGNED FOR POWER AMPLIFIER OF  
PORTABLE CASSETTE TAPE RECORDER APPLICATION.

. Recommended Supply Voltage :

TA7207P...V<sub>CC</sub>=6.0V

TA7208P...V<sub>CC</sub>=7.5V, 9.0V

. Output Power :

TA7207P...P<sub>OUT</sub>=0.95W(Typ.) at V<sub>CC</sub>=6.0V, R<sub>L</sub>=4Ω

TA7208P...P<sub>OUT</sub>=1.4W(Typ.) at V<sub>CC</sub>=7.5V, R<sub>L</sub>=4Ω

P<sub>OUT</sub>=2.0W(Typ.) at V<sub>CC</sub>=9.0V, R<sub>L</sub>=4Ω

THD=10%

. Minimum Operating Voltage: TA7207P...V<sub>CC</sub>=4.0V

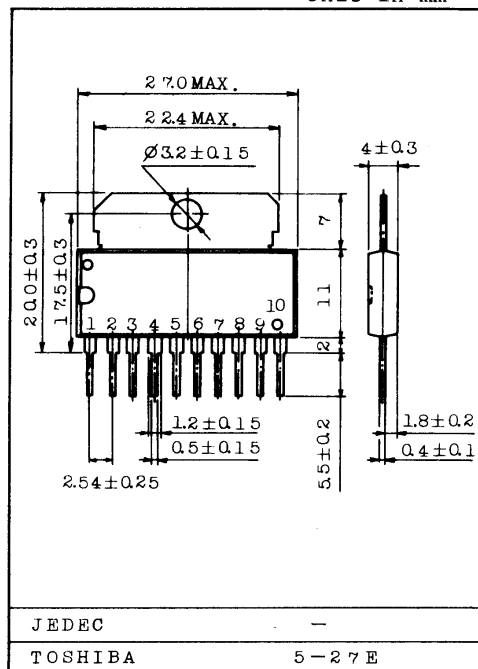
TA7208P...V<sub>CC</sub>=5.0V

. Low Quiescent Current

. Excellent Ripple Rejection

. Built in Turn-On Muting Circuit.

Unit in mm



### MAXIMUM RATINGS (Ta=25 °C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Supply Voltage	TA7207P	10	V
	TA7208P	14	
Output Current (Peak)	I <sub>O</sub> (peak)	1.8	A
Power Dissipation	P <sub>D</sub>	5.0	W
Operating Temperature	T <sub>opr</sub>	-20 ~ 75	°C
Storage Temperature	T <sub>stg</sub>	-55 ~ 150	°C



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### ELECTRICAL CHARACTERISTICS

(Unless otherwise specified  $R_L=4\Omega$ ,  $R_g=600\Omega$ ,  $R_f=150\Omega$ ,  $f=1\text{kHz}$ ,  $T_a=25^\circ\text{C}$ )

CHARACTERISTIC	SYMBOL	TEST CIR-CUIT	TEST CONDITION	TA7207P			TA7208P			UNIT	
				MIN.	TYP.	MAX.	MIN.	TYP.	MAX.		
Quiescent Current	$I_{CCQ}$	-	$V_{CC}=4.0\text{V}$	5.0	-	-	-	-	-	mA	
				$V_{CC}=5.0\text{V}$	-	-	-	55	-		-
				$V_{CC}=6.0\text{V}$	6.0	-	27.0	-	-		-
				$V_{CC}=9.0\text{V}$	-	-	-	7.0	-		30.0
				$V_{CC}=10\text{V}$	-	-	32.0	-	-		-
				$V_{CC}=14\text{V}$	-	-	-	-	-		35.0
Output Power	$P_{OUT}$	-	THD=10%	$V_{CC}=4\text{V}$	-	0.3	-	-	-	W	
				$V_{CC}=5\text{V}$	-	-	-	0.65	-		
				$V_{CC}=6\text{V}$	0.8	0.95	-	-	-		
				$V_{CC}=7.5\text{V}$	-	-	-	1.4	-		
				$V_{CC}=9\text{V}$	-	-	-	1.5	2.0		
Total Harmonic Distortion	THD	-	$P_{OUT}=100\text{mW}$	$V_{CC}=6\text{V}$	-	0.35	1.0	-	-	%	
				$V_{CC}=7.5\text{V}$	-	-	-	0.35	-		
				$V_{CC}=9\text{V}$	-	-	-	0.35	1.0		
Open Loop Voltage Gain	$G_{VO}$	-	$R_f=0$ $V_{IN}=0.245\text{mV}_{\text{rms}}$	$V_{CC}=6\text{V}$	-	72	-	-	-	dB	
				$V_{CC}=9\text{V}$	-	-	-	72	-		
Closed Loop Voltage Gain	$G_V$	-	$R_f=150\Omega$ $V_{IN}=3.9\text{mV}_{\text{rms}}$	$V_{CC}=6\text{V}$	-	46	-	-	-	dB	
				$V_{CC}=9\text{V}$	-	-	-	46	-		
Input Resistance	$R_{IN}$	-	$V_{OUT}=1\text{V}_{\text{rms}}$	$V_{CC}=6\text{V}$	25	30	-	-	-	k $\Omega$	
				$V_{CC}=9\text{V}$	-	-	-	25	30		
Output Noise Voltage	$V_{NO}$	-	$R_g=10\text{k}\Omega$ $BW=50\text{Hz}$ $\sim 20\text{kHz}$	$V_{CC}=6\text{V}$	-	-	1.0	-	-	mV	
				$V_{CC}=9\text{V}$	-	-	-	-	-		1.0

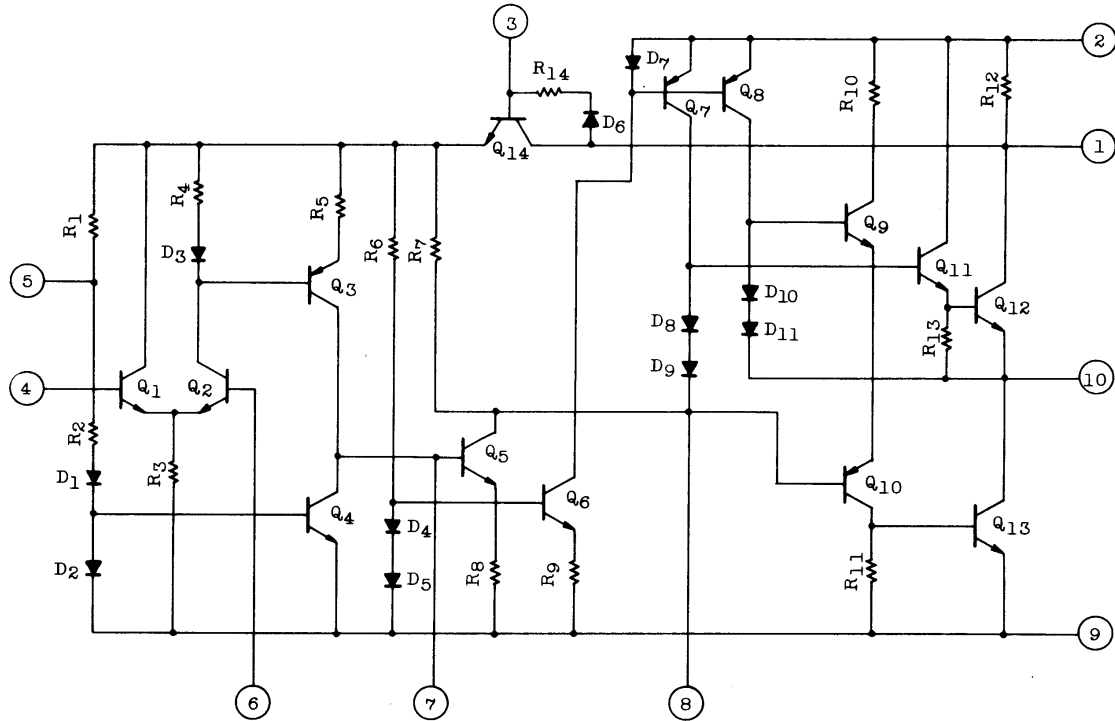


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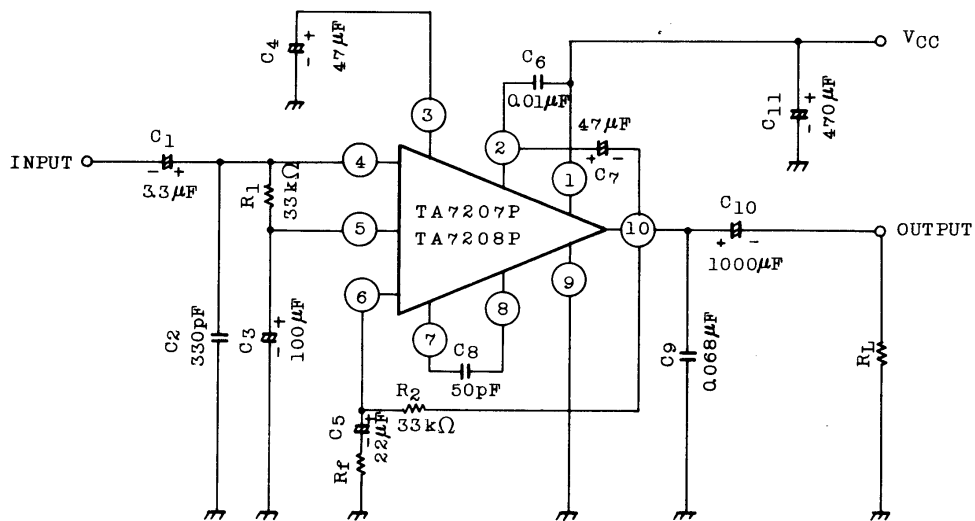
## TA7207P, TA7208P

### TECHNICAL DATA

#### EQUIVALENT CIRCUIT



#### TEST AND APPLICATION CIRCUIT

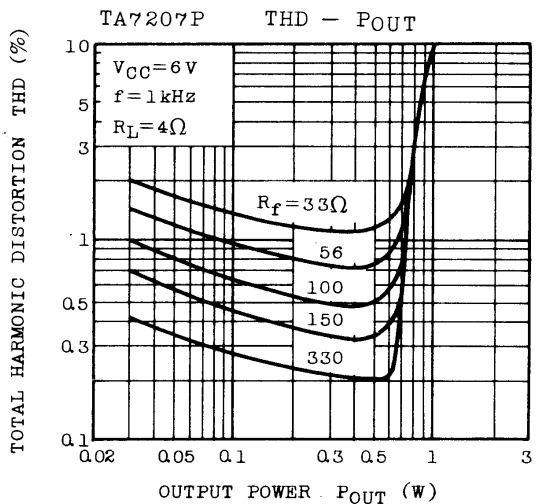
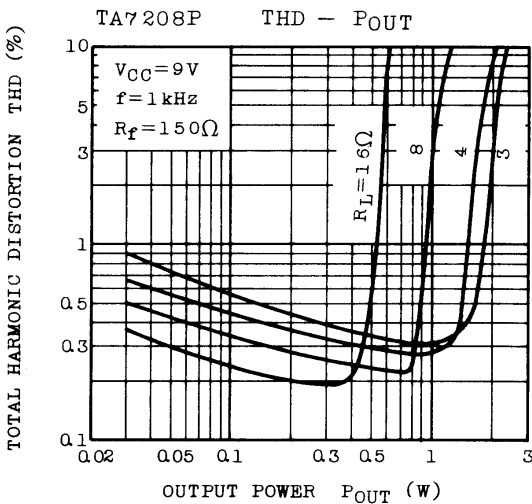
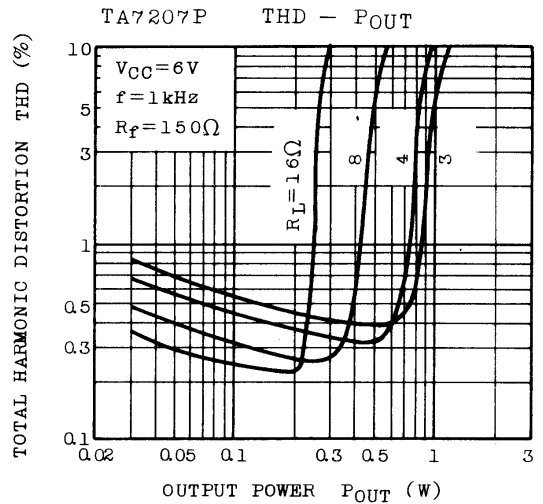
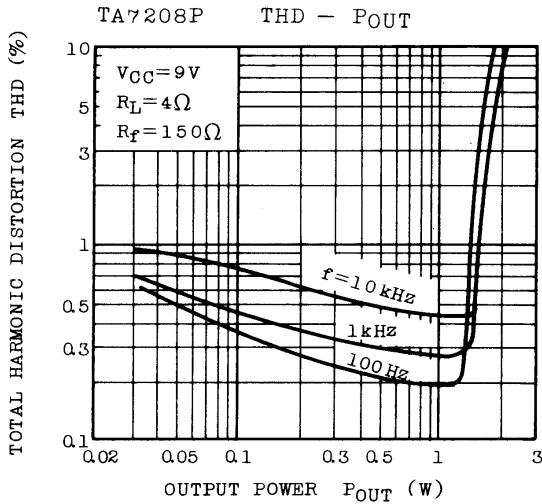
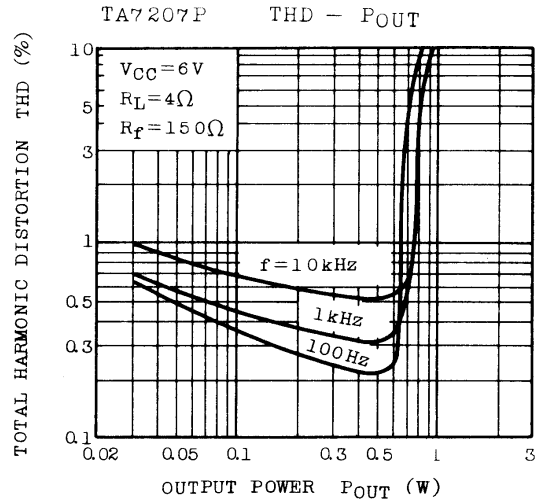
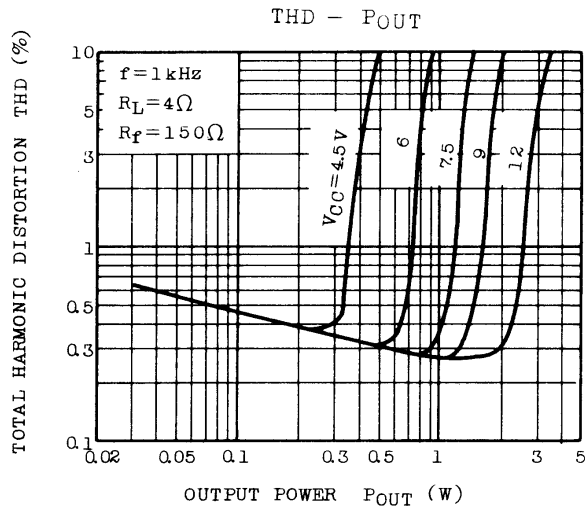




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### TECHNICAL DATA



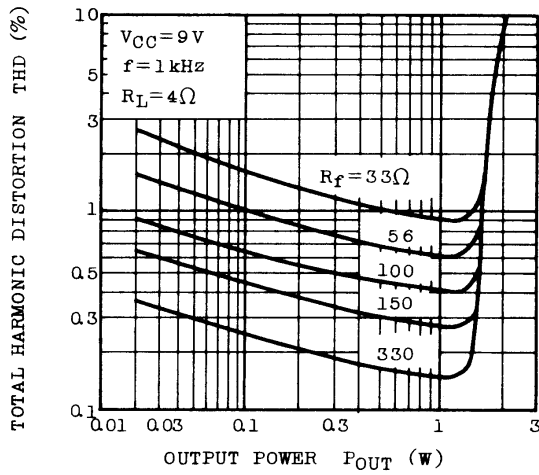


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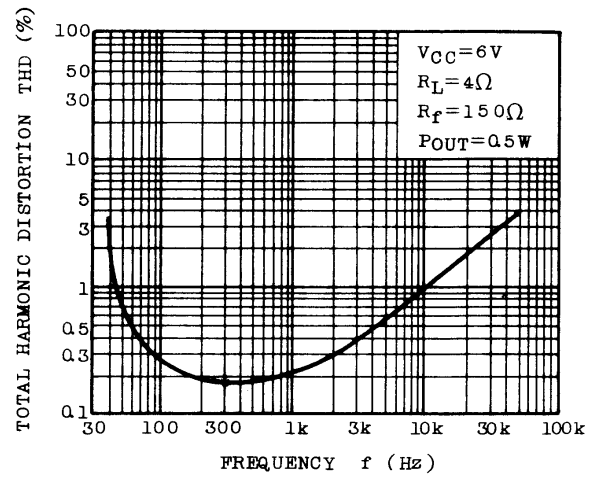
## TECHNICAL DATA

### TA7207P, TA7208P

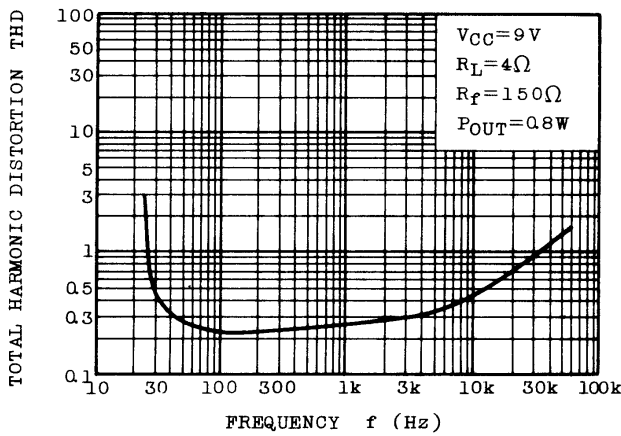
TA7208P THD - P<sub>OUT</sub>



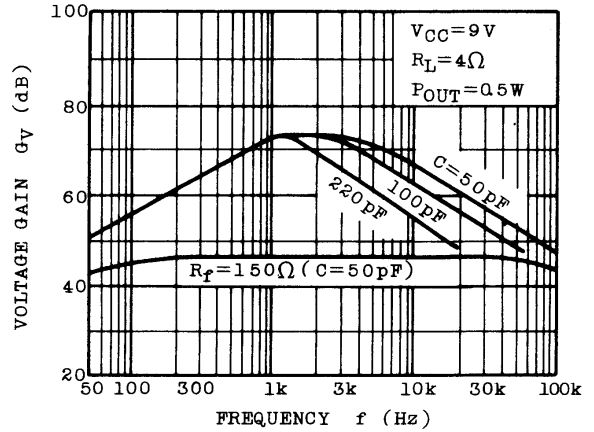
TA7207P THD - f



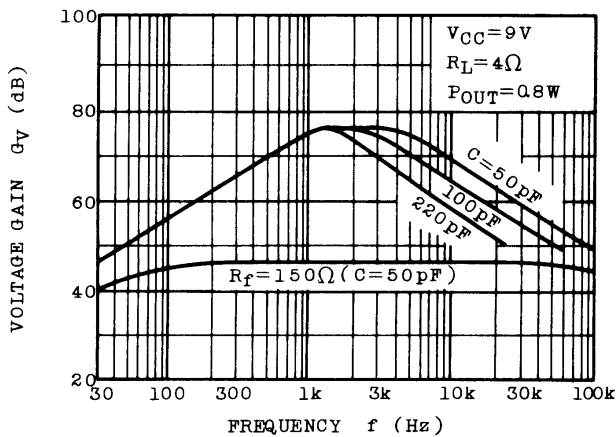
TA7208P THD - f

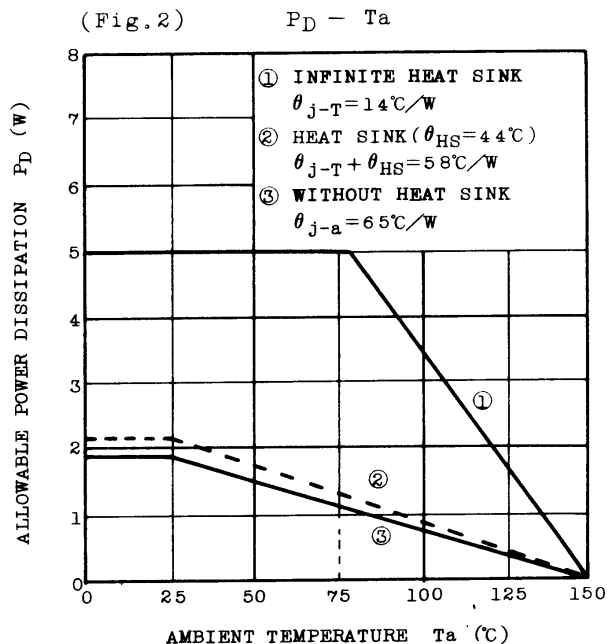
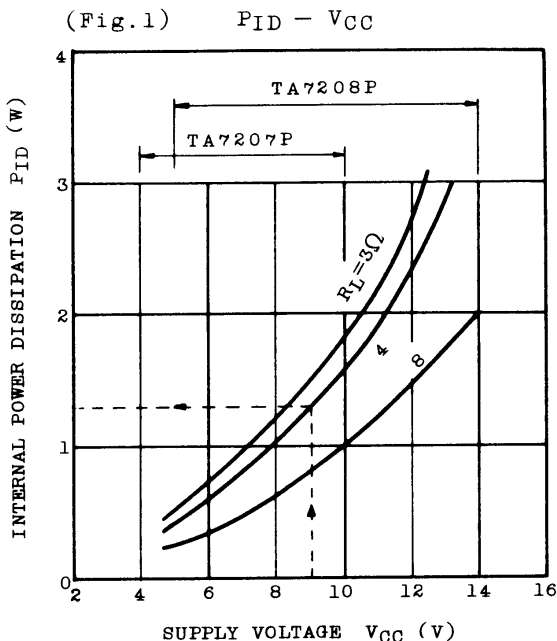


TA7207P G<sub>V</sub> - f



TA7208P G<sub>V</sub> - f





#### DESIGN OF HEAT SINK

The heat sink can be designed by using 'Internal Power Dissipation vs. Supply Voltage Characteristics' shown in Fig. 1 and 'Maximum Allowable Power Dissipation vs. Ambient Temperature Characteristics' shown in Fig.2. Junction to Tab and Junction to Ambient Thermal Resistance are follows.

$$\theta_{j-T} = 14^\circ\text{C}/\text{W} \text{ (Max.)} \dots\dots\dots \text{Junction to Tab}$$

$$\theta_{j-a} = 65^\circ\text{C}/\text{W} \text{ (Max.)} \dots\dots\dots \text{Junction to Ambient}$$

#### 1. Operating Without External Heat Sink

In this case, Maximum Allowable Power Dissipation ( $P_D$ ) is given in the next equation.

$$P_D = \frac{T_{j \text{ Max}} - T_a}{\theta_{j-a}} \dots\dots\dots (1)$$

where

$T_{j \text{ Max}}$  ; Maximum junction temperature  
 (equal to  $T_{stg \text{ Max}}$  ( $150^\circ\text{C}$ ))

$T_a$  ; Ambient temperature.

$\theta_{j-a}$  ; Thermal Resistance between junction of IC and air.  
 ( $\theta_{j-a}$  is  $65^\circ\text{C}/\text{W}$  from Fig.2)



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In case of  $T_a=25^{\circ}\text{C}$

$$P_D = \frac{150 - 75}{65} = 1.1\text{W}$$

In the following operation, external heat sink is not necessary. Because the internal Power dissipation is less than 1.1W under this condition.

$$V_{CC} \leq 7.5\text{V}, R_L \geq 3\Omega$$

### 2. Operating with External Heat Sink

The required thermal resistance of external heat sink ( $\theta_{HS}$ ) is given in the following equation.

$$\theta_{HS} = \frac{T_{j \text{ max}} - T_a}{P_{ID}} - \theta_{j-T} \dots\dots\dots(2)$$

where

$\theta_{j-T}$  ; Thermal resistance between junction and tab of IC  
( $\theta_{j-T}$  is  $14^{\circ}\text{C/W}$ )

Now, we suppose to use TA7208P at  $V_{CC}=9\text{V}$ ,  $R_L=4\Omega$ ,  $T_a=75^{\circ}\text{C}$  max.

In this case,  $P_{ID}$  is more than 1.1W, external heat sink is necessary. The thermal resistance of heat sink is given from equation (2). (From Fig.1,  $P_{ID}=1.3\text{W}$ )

$$\theta_{HS} = \frac{150 - 75}{1.3} - 14 = 44^{\circ}\text{C/W}$$

This value is correspond to that of  $4 \sim 5 \text{ cm}^2 \times 2 \text{ mm}$  Aluminum plate thermal resistor.

Table 1 shows thermal resistance value of required external heat sink for various conditions. ( $V_{CC}$  and  $R_L$ )

$R_L$ ( $\Omega$ ) \ $V_{CC}$ (V)	6.0	7.5	9.0
3			$36^{\circ}\text{C/W}$ (1)
4			$44^{\circ}\text{C/W}$ (2)
6			

The area of shaded portion external heat sink is unnecessary.

(1) ; Equivalent to  $5 \sim 6 \text{ cm}^2 \times 1 \sim 2 \text{ mm}$  Aluminum.

(2) ; Equivalent to  $4 \sim 5 \text{ cm}^2 \times 1 \sim 2 \text{ mm}$  Aluminum.